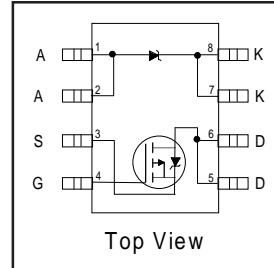


# International **IR** Rectifier

## IRF7322D1

**FETKY™ MOSFET / Schottky Diode**

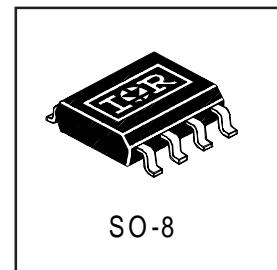
- Co-packaged HEXFET® Power MOSFET and Schottky Diode
- Ideal For Buck Regulator Applications
- P-Channel HEXFET
- Low  $V_F$  Schottky Rectifier
- Generation 5 Technology
- SO-8 Footprint



$V_{DSS} = -20V$   
 $R_{DS(on)} = 0.058\Omega$   
 Schottky  $V_f = 0.39V$

### Description

The **FETKY** family of co-packaged MOSFETs and Schottky diodes offers the designer an innovative, board space saving solution for switching regulator and power management applications. Generation 5 HEXFET Power MOSFETs utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. Combining this technology with International Rectifier's low forward drop Schottky rectifiers results in an extremely efficient device suitable for use in a wide variety of portable electronics applications.



The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics. The SO-8 package is designed for vapor phase, infrared or wave soldering techniques.

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter		Maximum	Units
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V$	-5.3	A
$I_D @ T_A = 70^\circ C$		-4.3	
$I_{DM}$	Pulsed Drain Current ①	-43	
$P_D @ T_A = 25^\circ C$	Power Dissipation	2.0	W
$P_D @ T_A = 70^\circ C$		1.3	
$V_{GS}$	Linear Derating Factor	16	mW/°C
$V_{GS}$	Gate-to-Source Voltage	± 12	V
$dv/dt$	Peak Diode Recovery $dv/dt$ ②	-5.0	V/ns
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Resistance Ratings

Parameter		Maximum	Units
$R_{θJA}$	Junction-to-Ambient ④	62.5	°C/W

#### Notes:

- ① Repetitive rating; pulse width limited by maximum junction temperature (see figure 9)
- ②  $I_{SD} \leq -2.9A$ ,  $di/dt \leq -77A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq 150^\circ C$
- ③ Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$
- ④ Surface mounted on FR-4 board,  $t \leq 10sec$ .

**MOSFET Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

Parameter		Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	-20	—	—	V	$V_{\text{GS}} = 0\text{V}$ , $I_D = -250\mu\text{A}$
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	0.049	0.062	$\Omega$	$V_{\text{GS}} = -4.5\text{V}$ , $I_D = -2.9\text{A}$ ③
		—	0.082	0.098		$V_{\text{GS}} = -2.7\text{V}$ , $I_D = -1.5\text{A}$ ③
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	-0.70	—	—	V	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = -250\mu\text{A}$
$g_f$	Forward Transconductance	—	5.9	—	S	$V_{\text{DS}} = -10\text{V}$ , $I_D = -1.5\text{A}$
$I_{\text{DSS}}$	Drain-to-Source Leakage Current	—	—	-1.0	$\mu\text{A}$	$V_{\text{DS}} = -16\text{V}$ , $V_{\text{GS}} = 0\text{V}$
		—	—	-25		$V_{\text{DS}} = -16\text{V}$ , $V_{\text{GS}} = 0\text{V}$ , $T_J = 55^\circ\text{C}$
$I_{\text{GSS}}$	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{\text{GS}} = -12.0\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}} = 12.0\text{V}$
$Q_g$	Total Gate Charge	—	19	29	nC	$I_D = -2.9\text{A}$
$Q_{\text{gs}}$	Gate-to-Source Charge	—	4.0	6.1		$V_{\text{DS}} = -16\text{V}$
$Q_{\text{gd}}$	Gate-to-Drain ("Miller") Charge	—	7.7	12		$V_{\text{GS}} = -4.5\text{V}$ (see figure 6) ③
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	15	22	ns	$V_{\text{DD}} = -10\text{V}$
$t_r$	Rise Time	—	40	60		$I_D = -2.9\text{A}$
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	42	63		$R_G = 6.0\Omega$
$t_f$	Fall Time	—	49	73		$R_D = 3.4\Omega$ ③
$C_{\text{iss}}$	Input Capacitance	—	780	—	pF	$V_{\text{GS}} = 0\text{V}$
$C_{\text{oss}}$	Output Capacitance	—	470	—		$V_{\text{DS}} = -15\text{V}$
$C_{\text{rss}}$	Reverse Transfer Capacitance	—	240	—		$f = 1.0\text{MHz}$ (see figure 5)

**MOSFET Source-Drain Ratings and Characteristics**

Parameter		Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	-2.5	A	
$I_{\text{SM}}$	Pulsed Source Current (Body Diode)	—	—	-21		
$V_{\text{SD}}$	Body Diode Forward Voltage	—	—	-1.2	V	$T_J = 25^\circ\text{C}$ , $I_S = -2.9\text{A}$ , $V_{\text{GS}} = 0\text{V}$
$t_{\text{rr}}$	Reverse Recovery Time (Body Diode)	—	47	71	ns	$T_J = 25^\circ\text{C}$ , $I_F = -2.9\text{A}$
$Q_{\text{rr}}$	Reverse Recovery Charge	—	49	73	nC	$dI/dt = 100\text{A}/\mu\text{s}$ ③

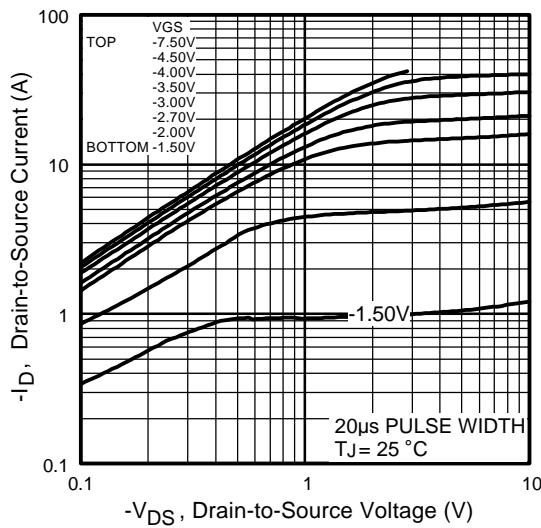
**Schottky Diode Maximum Ratings**

	Parameter	Max.	Units	Conditions	
$I_{\text{F(av)}}$	Max. Average Forward Current	2.7	A	50% Duty Cycle. Rectangular Wave, $T_A = 25^\circ\text{C}$	
		2		See Fig. 14 $T_A = 70^\circ\text{C}$	
$I_{\text{SM}}$	Max. peak one cycle Non-repetitive Surge current	120	A	5μs sine or 3μs Rect. pulse	Following any rated load condition & with $V_{\text{RRM}}$ applied
		11		10ms sine or 6ms Rect. pulse	

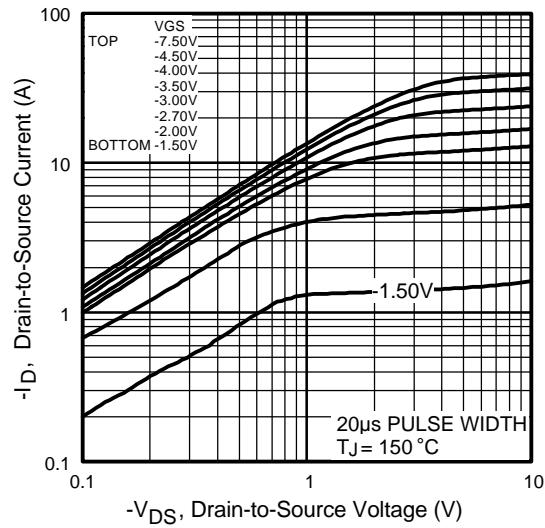
**Schottky Diode Electrical Specifications**

	Parameter	Max.	Units	Conditions	
$V_{\text{FM}}$	Max. Forward voltage drop	0.50	V	$I_F = 1.0\text{A}$ , $T_J = 25^\circ\text{C}$	
		0.62		$I_F = 2.0\text{A}$ , $T_J = 25^\circ\text{C}$	
		0.39		$I_F = 1.0\text{A}$ , $T_J = 125^\circ\text{C}$	
		0.57		$I_F = 2.0\text{A}$ , $T_J = 125^\circ\text{C}$ .	
$I_{\text{RM}}$	Max. Reverse Leakage current	0.02	mA	$V_R = 20\text{V}$	$T_J = 25^\circ\text{C}$
		8			$T_J = 125^\circ\text{C}$
$C_t$	Max. Junction Capacitance	92	pF	$V_R = 5\text{Vdc}$ ( 100kHz to 1 MHz) $25^\circ\text{C}$	
$dv/dt$	Max. Voltage Rate of Change	3600	V/μs	Rated $V_R$	

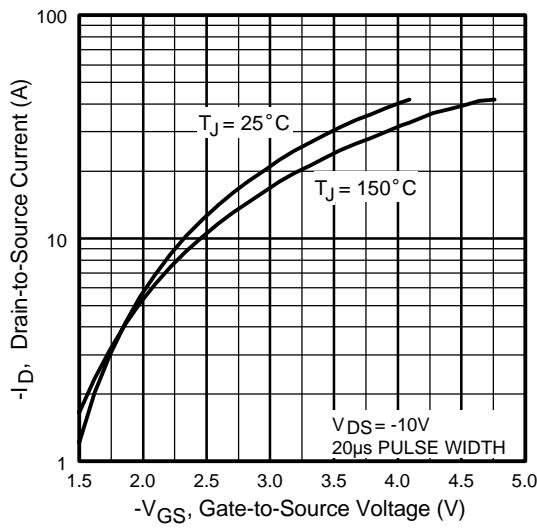
### Power Mosfet Characteristics



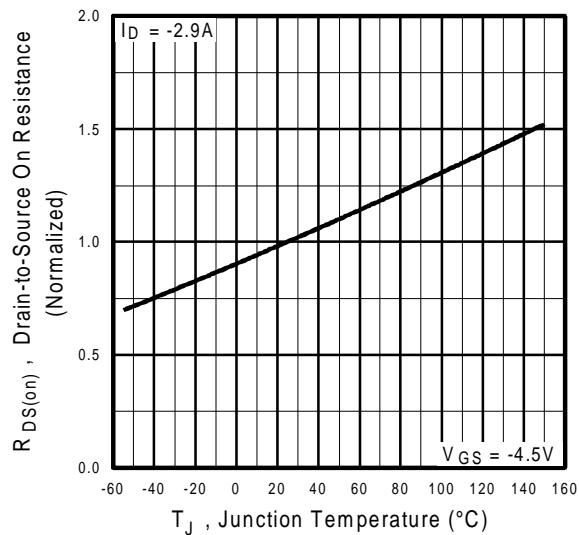
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics



**Fig 3.** Typical Transfer Characteristics

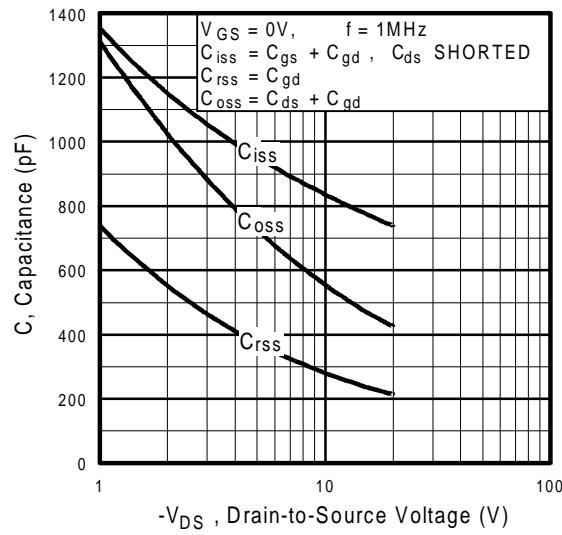


**Fig 4.** Normalized On-Resistance Vs. Temperature

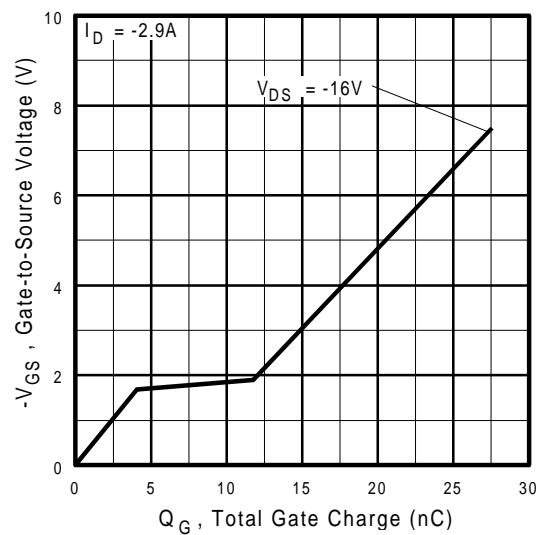
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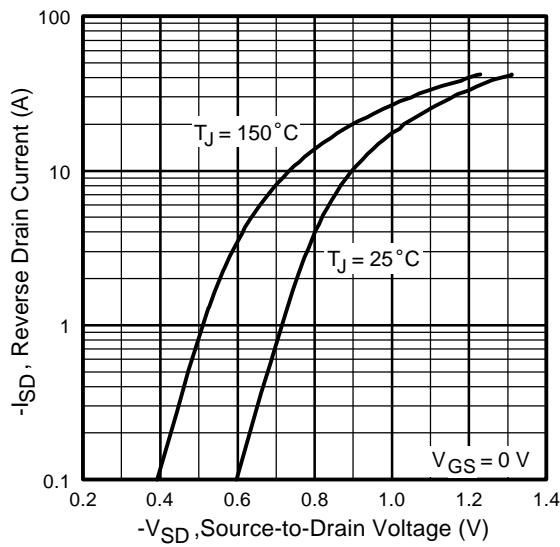
## Power Mosfet Characteristics



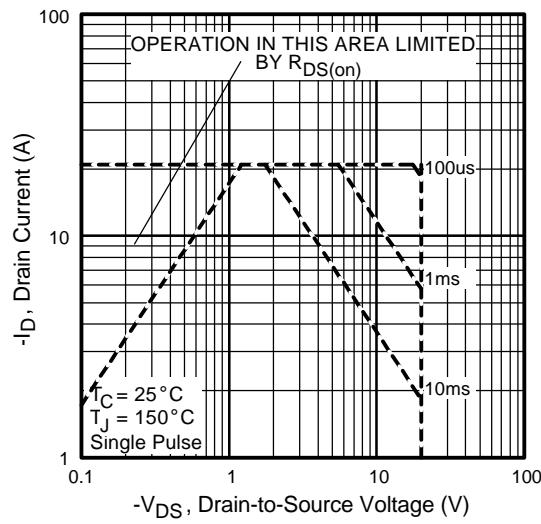
**Fig 5.** Typical Capacitance Vs.  
Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs.  
Gate-to-Source Voltage

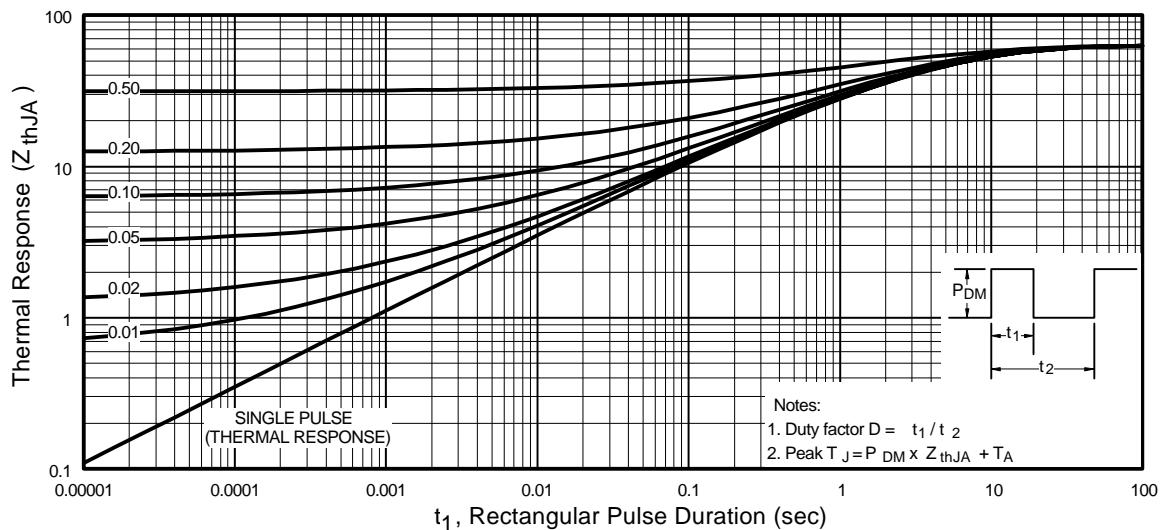


**Fig 7.** Typical Source-Drain Diode  
Forward Voltage

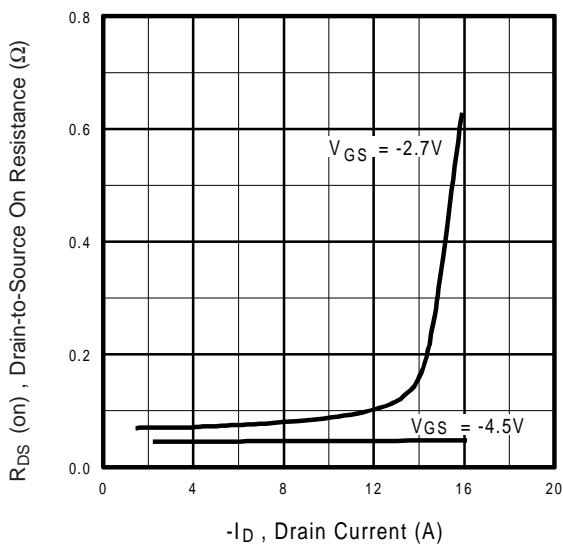


**Fig 8.** Maximum Safe Operating Area

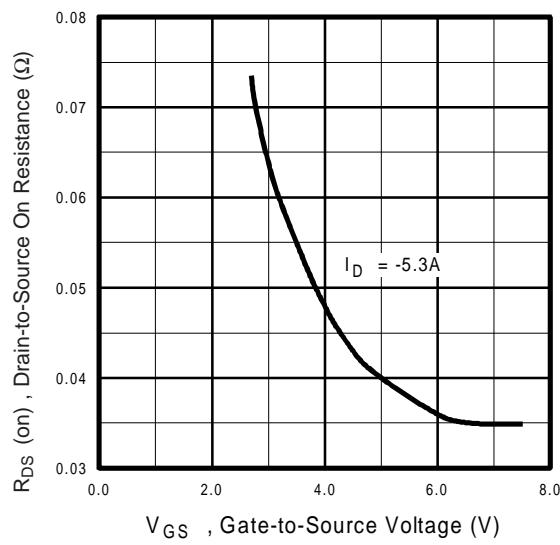
### Power Mosfet Characteristics



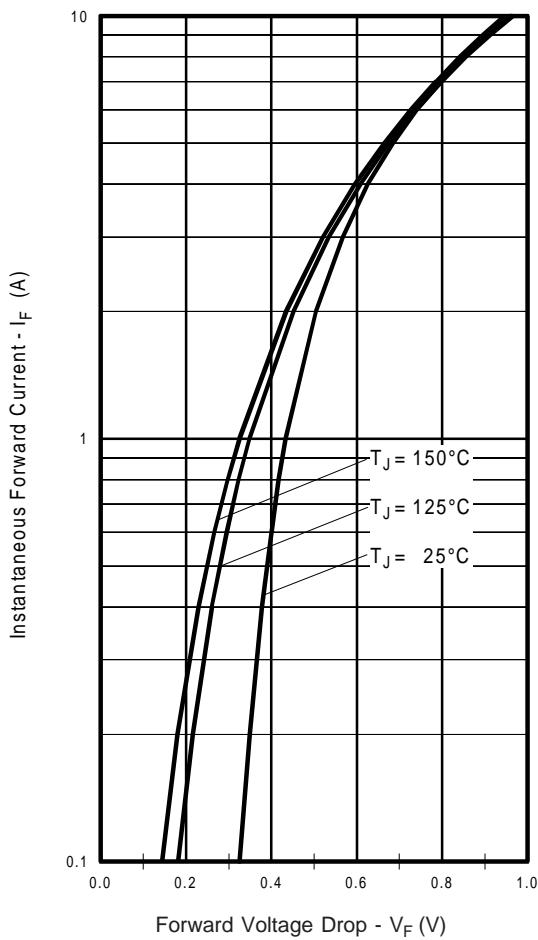
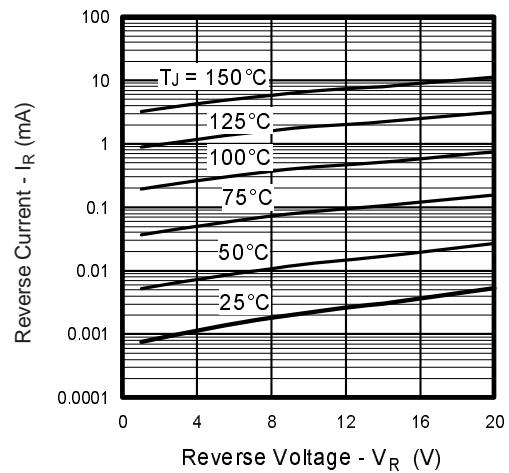
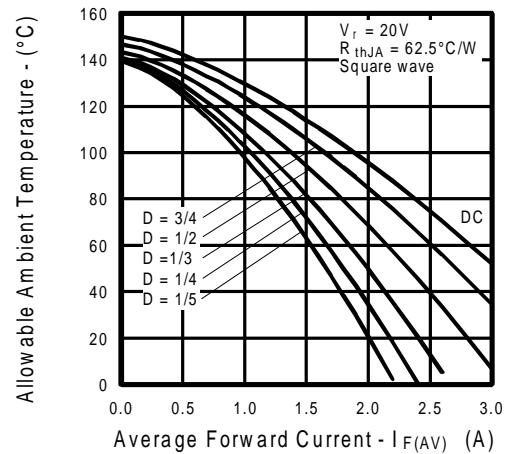
**Fig 9.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



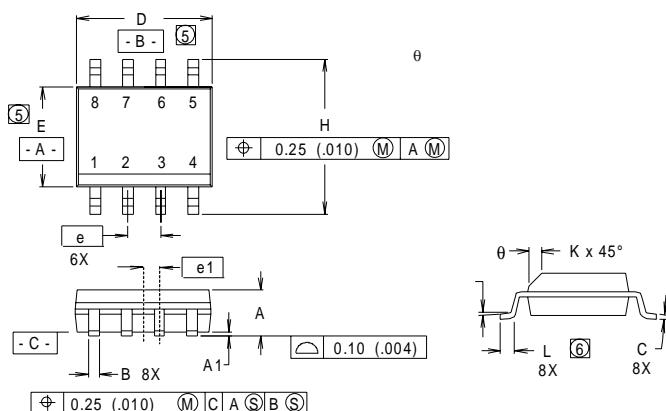
**Fig 10.** Typical On-Resistance Vs. Drain Current



**Fig 11.** Typical On-Resistance Vs. Gate Voltage

**Schottky Diode Characteristics****Fig. 12** - Typical Forward Voltage Drop Characteristics**Fig. 13** - Typical Values of Reverse Current Vs. Reverse Voltage**Fig.14** - Maximum Allowable Ambient Temp. Vs. Forward Current

## SO-8 Package Details

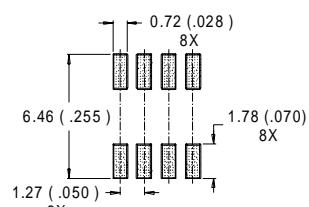


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS  
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.006).
- ⑥ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

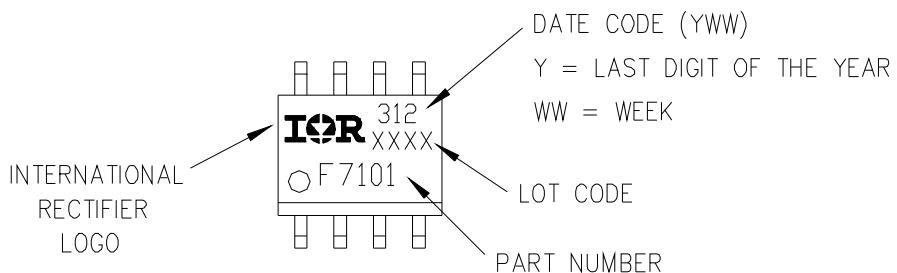
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
B	.014	.018	0.36	0.46
C	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	0.16	.050	0.41	1.27
θ	0°	8°	0°	8°

RECOMMENDED FOOTPRINT



## Part Marking

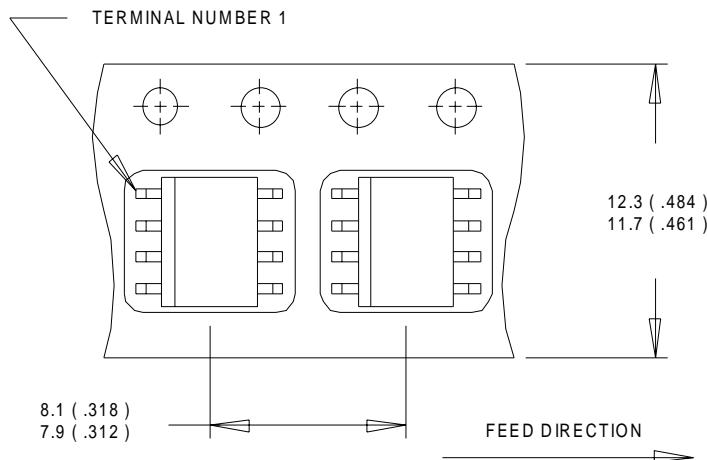
EXAMPLE: THIS IS AN IRF7101



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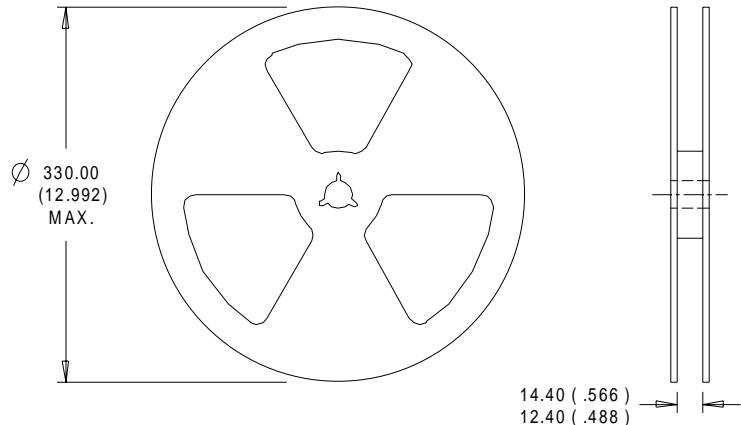
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## Tape and Reel



### NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



### NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

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**IR** Rectifier

**WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331

**IR GREAT BRITAIN:** Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

**IR CANADA:** 15 Lincoln Court, Brampton, Ontario L6T3Z2, Tel: (905) 453 2200

**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

**IR FAR EAST:** K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo Japan 171 Tel: 81 3 3983 0086

**IR SOUTHEAST ASIA:** 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994 Tel: ++ 65 221 8371

**IR TAIWAN:** 16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan Tel: 886-2-2377-9936

<http://www.irf.com/> Data and specifications subject to change without notice . 3/99

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